

Printed board assemblies - Part 3: Sectional
specification - Requirements for through-hole mount
soldered assemblies

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

See Eesti standard EVS-EN 61191-3:2017 sisaldab Euroopa standardi EN 61191-3:2017 ingliskeelset teksti.	This Estonian standard EVS-EN 61191-3:2017 consists of the English text of the European standard EN 61191-3:2017.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas.	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation.
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English Version

**Printed board assemblies - Part 3: Sectional specification -
Requirements for through-hole mount soldered assemblies
(IEC 61191-3:2017)**

Ensembles de cartes imprimées - Partie 3: Spécification
intermédiaire - Exigences relatives à l'assemblage par
brasage de trous traversants
(IEC 61191-3:2017)

Elektronikaufbauten auf Leiterplatten - Teil 3:
Rahmenspezifikation - Anforderungen an gelötete
Baugruppen in Durchsteckmontage
(IEC 61191-3:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 91/1375/CDV, future edition 2 of IEC 61191-3, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61191-3:2017.

The following dates are fixed:

- latest date by which the document has to be (dop) 2018-04-04
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2020-07-04
standards conflicting with the
document have to be withdrawn

This document supersedes EN 61191-3:1998.

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Endorsement notice

The text of the International Standard IEC 61191-3:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20.
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58.
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1.
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2.
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3.
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4.
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-5.
IEC 61188-7	NOTE	Harmonized as EN 61188-7.
IEC 61189-2	NOTE	Harmonized as EN 61189-2.
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2.
IEC 61193-1	NOTE	Harmonized as EN 61193-1.
IEC 61193-3	NOTE	Harmonized as EN 61193-3.
IEC 62326-1	NOTE	Harmonized as EN 62326-1.
IEC 62326-4	NOTE	Harmonized as EN 62326-4.

IEC 62326-4-1

NOTE Harmonized as EN 62326-4-1.

ISO 9001

NOTE Harmonized as EN ISO 9001.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-
IEC 61191-1	2013	Printed board assemblies -- Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	2013
IPC-A-610	-	Acceptability of Electronics Assemblies	-	-

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